

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	(power near (CMOS MOS FET MIS switch\$3)) with (IC (integrated near circuit)) with (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:01
L2	8	((("6351031") or ("5475565") or ("6330158") or ("5625536")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/06/17 11:32
L3	0	("module\$1").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/06/17 11:33
L4	630391	module\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 11:33
L5	91046	4 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:56
L6	8925	5 and (power near2 (chip\$1 die\$1 IC\$1 circuit\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55
L7	327	6 and (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:02
L8	1048	6 and (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55

L9	531	8 and ((thermal heat) near (dissipat\$3 sink))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:36
L10	413	9 and (resin seal\$3 encapsulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:56
L11	116	10 and gate\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 11:39
L12	16	("5227663"   "5371404"   "5641987"   "5785799"   "5834839"   "5866953"   "5872395"   "5891753"   "5977626"   "6069023"   "6150193"   "6191360"   "6201301"   "6229702"   "6316829"   "6462405").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 12:25
L13	192	7 and ((thermal heat) near (dissipat\$3 sink))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:37
L14	195	7 and ((thermal heat) near (dissipat\$3 sink spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55
L15	162	14 and (resin seal\$3 encapsulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:37
L16	24993	5 and (power with (chip\$1 die\$1 IC\$1 circuit\$1 device\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:06
L17	2466	16 and (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55

L18	1050	17 and ((thermal heat) near (dissipat\$3 sink spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:08
L19	807	18 and (resin seal\$3 encapsulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07
L20	807	19 and (substrate carrier\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:56
L21	339	20 and (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:57
L22	315	21 and packag\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:58
L23	139	22 and driv\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:59
L24	5	("20020049042"   "6072122"   "6114413"   "6320543"   "6630727").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 14:04
L25	2	("6165885"   "6239486").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 14:07
L26	3045	(power near (CMOS MOS FET MIS switch\$3)) with (IC (integrated near circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:27
L27	2	26 and (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07

L28	1228451	(power with (chip\$1 die\$1 IC\$1 circuit\$1 device\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:06
L29	149989	28 and (driv\$3 near (chip\$1 die\$1 IC\$1 circuit\$1 device\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:06
L30	347	29 and (flip near chip near bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07
L31	238	30 and (resin seal\$3 encapsulat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07
L32	95	31 and ((thermal heat) near (dissipat\$3 sink spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:08
L33	132	(power near (CMOS MOS FET MIS switch\$3)) with (driv\$3 near (IC (integrated near circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:41
L34	17	33 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:28
L35	4	("5656550"   "5976912"   "6238952"   "6294830").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 15:38
L36	8	("5559364"   "5580466"   "6001671"   "6025650"   "6063139"   "6228676"   "6410363"   "6451627").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 15:39
L37	115	33 not 34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:42

L38	4	("5109318"   "5373418"   "5375040"   "5514917").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 15:46
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